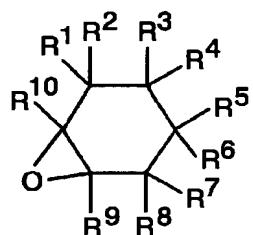


CLAIMS

1. A heat-curable resin composition comprising an alicyclic epoxy compound (a) having a structure represented by the following general formula (1),

General formula (1)



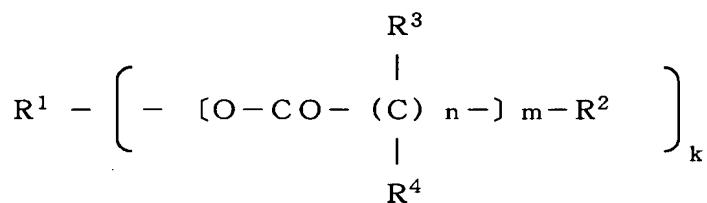
[In the general formula (1): R¹ to R¹⁰ each represent hydrogen, or a saturated or unsaturated hydrocarbon group having 1 to 20 carbon atoms (an ether bond, an ester bond, or an alcoholic hydroxyl group may be included in the hydrocarbon group); R¹ to R¹⁰ may each represent a residue derived by removing any one of R¹ to R¹⁰ from the structure represented by the general formula (1), or a residue derived by removing hydrogen from any one of R¹ to R¹⁰; and the phrase "in the hydrocarbon group" refers to "inside the hydrocarbon group", "at terminals of the hydrocarbon group", or "within bonds of the hydrocarbon group"], a cationic polymerization initiator (i), and optionally a surfactant (e).

2. A heat-curable resin composition according to claim 1, further comprising a polyol (b) having two or more hydroxyl groups on

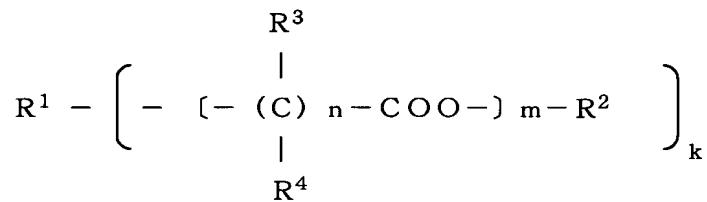
terminals.

3. A heat-curable resin composition comprising an alicyclic epoxy compound (a') having a structure represented by the following general formula (2),

General formula (2)



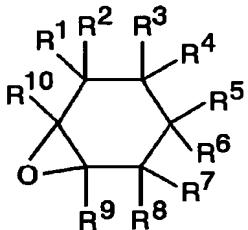
or



[In the general formula (2): R^1 represents hydrogen, or a hydrocarbon group of a valence k having 1 to 20 carbon atoms (an ether bond, an ester bond, or an alcoholic hydroxyl group may be included in the hydrocarbon group); R^2 represents hydrogen, a hydroxyl group, or a hydrocarbon group having 1 to 20 carbon atoms (an ether bond, an ester bond, or an alcoholic hydroxyl group may be included in the hydrocarbon group); at least one of R^1 and R^2 may represent a residue derived by removing any one of R^1 to R^{10} from the structure represented by the following general formula (1); R^3 and R^4 each represents hydrogen, or a hydrocarbon group having 1 to 20 carbon atoms; a plurality of R^3 's and R^4 's may be the same or different from

each other; "n" represents an integer of 3 to 10; "m" represents an integer of 2 to 10; "k" represents an integer of 1 to 10; when "k" is 2 or more, "k" pieces of group structures (that is, "k" pieces of ns, ms, R²s, R³s, and R⁴s) may be the same or different from each other; and the phrase "in the hydrocarbon group" refers to "inside the hydrocarbon group", "at terminals of the hydrocarbon group", or "within bonds of the hydrocarbon group"],

General formula (1)



[In the general formula (1): R¹ to R¹⁰ each represent hydrogen, or a saturated or unsaturated hydrocarbon group having 1 to 20 carbon atoms (an ether bond, an ester bond, or an alcoholic hydroxyl group may be included in the hydrocarbon group); R¹ to R¹⁰ may each represent a residue derived by removing any one of R¹ to R¹⁰ from the structure represented by the general formula (1), or a residue derived by removing hydrogen from any one of R¹ to R¹⁰; and the phrase "in the hydrocarbon group" refers to "inside the hydrocarbon group", "at terminals of the hydrocarbon group", or "within bonds of the hydrocarbon group"], a cationic polymerization initiator (i), and optionally a surfactant (e).

4. A curable-resin composition according to claim 1, characterized in that the surfactant (e) comprises a silicon-based surfactant (e1) having a dimethylsiloxane skeleton and/or a fluorine-based surfactant (e2) having hydrophobic groups of a hydrocarbon-based surfactant entirely or partially substituted with fluorine atoms.

5. A curable-resin composition according to claim 2, characterized in that the surfactant (e) comprises a silicon-based surfactant (e1) having a dimethylsiloxane skeleton and/or a fluorine-based surfactant (e2) having hydrophobic groups of a hydrocarbon-based surfactant entirely or partially substituted with fluorine atoms.

6. A curable-resin composition according to claim 3, characterized in that the surfactant (e) comprises a silicon-based surfactant (e1) having a dimethylsiloxane skeleton and/or a fluorine-based surfactant (e2) having hydrophobic groups of a hydrocarbon-based surfactant entirely or partially substituted with fluorine atoms.

7. A cured product, which is obtained by heat curing the heat-curable resin composition according to any one of claims 1 to 6.

8. A cured product according to claim 7, which is used for an adhesive or an encapsulant.

9. A cured product according to claim 7, wherein a warping by shrinkage in curing is 15 mm or less through a measurement method A, 6 mm or less through a measurement method B.

10. A cured product according to claim 8, wherein a warping by shrinkage in curing is 15 mm or less through a measurement method A, 6 mm or less through a measurement method B.